ll rights strictly res form whatever is not permitted without written authority fro Property of FCL Copyright FCL. interoffe sous quelque Forme que ce soft sans autorisation ecrite du propietaire Propriete de c FCL. Broits de reproduction FCL FCI Œ NOTE, ROHS DUMPATIBLE PRODUCT SPECIFICATIONS

a. PLATING, 'L'P' NEANS THE PRODUCT IS LEAD FREE, GOLD FLASH PLATING OVER 1:27Lm MIN

NICKEL UNDERPLATE ON SOLIER AREA

b. MANUFACTURING PROCESS COMPATIBILITY THE HOUSING WILL VITHSTAND EXPOSURE TO 260C\*±5C\*

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SOLIDER BATH TEMPERATURE FOR 10 SECONDS IN IR-REFLOV APPLICATION PRDI NO 10042917-XXX 15.70 11.9±0.1 💠 0.10 C 11.D±Q.L + O.LD C 1.00號×2 Ф <u>.</u> 0 ㅠ 2.54 XZ=5.08 2 2 16.45 [5,25±0,20 2.54(PITCH) 9.53 B0.0 + B 0 5 #2.0(SUCKER POSITION(MIN) 6.10 ▶-⊡ index sheet mat'l, ∞de 0.70x6 TO5-0280 7.6(REF) TO4-0350 ecn no ACAD sheet LENBIOU 8/19/04 12/12/D date œ 0.050x6 0.D50X4 0.10 incar engr JASON HSU 8/19/04: chr STERLING UN 8/19/04: appd HC LIOV 8/19/04: tolerances unless otherwise specified STERLING LIN 8/19/04'
HC LIOU 8/19/04' JASON HSU 8/18/04° .X ±.50 .XX ±.25 .XXX ±.10 0° ±2° 3.PART NUMBER DESCRIPTION: 2.FINISH: 1.MATERIAL: HOUSING: HIGH TEMPERATURE POLYMER OVER MIN 1.25um(50u-inch)Ni SOLDER AREA: MIN 0.025um(1.0u-inch)Au SELECT GOLD OVER MIN 1.25um (50u-inch) Ni CONTACTS PLATING: CONTACT AREA: CONTACTS: COPPER ALLOY. 10042917-0 0 × ᄕ METAL HOLD DOWN: STAINLESS STEEL. 2.54(PITCH) 900ge CUSTOMER projection 0.80 <del>ф</del> Д ₹ PCB LAYOUT **№** product family SIM CARD size dwg no - PLATING
1: 30" Au
2: 100" Au
3: 15" Au
4: GOLD FLASH. ≨ 1.59 9.513 - LF: LEAD FREE 10042917 FC! ≫ cage SLIDING SIM CARD 22526 CONNECTOR 1.83 352 \_6.22(Nin) .6.22(Min). sheet 6000

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